

# TGP2000PT

## Thermally Conductive Gap Pad

### BENEFITS AND FEATURES

- High thermal performance
- Ultra-soft
- High compressibility
- Excellent gap-filling capability
- Natural tacky
- Extreme low oil bleeding

### OVERVIEW

Honeywell TGP2000PT Thermally Conductive Gap Pad provides high thermal performance and excellent thermal reliability. The material's putty-like design enables excellent gap-filling capability for applications with large dimensional variances. Special surface reinforcement enables easier handling for operators during high volume assembly. The product is naturally tacky and requires no additional adhesive to mate to heat source and heat sink. Products are available in thicknesses ranging from 0.5mm to 5.0mm.

### TYPICAL APPLICATIONS

- EV battery & charging station
- Automotive electronics
- Power devices & modules
- Telecommunications & network servers

### STORAGE & USE

Shelf life 12 months at 0-35°C, <65%RH

Property	TGP2000PT	Test Method
Color	Pink	Visual
Thickness (mm)*	0.5-5	ASTM D374
Specific Gravity	2.9	ASTM D792
Hardness (Shore00)	5	ASTM D2240
Thermal Conductivity (W/m-K)	2.5	ASTM D5470
Thermal Impedance (°C-in <sup>2</sup> /W)(1mm@10psi) (Typical Value)	0.65	ASTM D5470
Dielectric Constant@1MHz	6	ASTM D150
Volume Resistivity (ohm-cm)	4 x 10 <sup>13</sup>	ASTM D257
Flammability Rating	V-0	UL94

\*Thickness range: 0.5-5.0mm with 0.25mm incremental  
 Thickness Tolerance: >=1mm, ±10%  
 0.5-1mm, ±0.1mm

### Honeywell Electronic Materials

USA: 1-509-252-2102  
 Mainland China: 400-840-2233  
 Germany: 49-5137-999-9199  
 Japan: 81-3-6730-7092  
 Korea: 82-2-3483-5076  
 Singapore: 65-6580-3593  
 Taiwan: 886-3-6580300 ext.312

[www.electronicmaterials.com](http://www.electronicmaterials.com)

Although all statements and information contained herein are believed to be accurate and reliable, they are presented without guarantee or warranty of any kind, express or implied. Information provided herein does not relieve the user from the responsibility of carrying out its own tests and experiments, and the user assumes all risks and liability for use of the information and results obtained. Statements or suggestions concerning the use of materials and processes are made without representation or warranty that any such use is free of patent infringement and are not recommendations to infringe any patent. The user should not assume that all toxicity data and safety measures are indicated herein or that other measures may not be required.